

INTRODUCING THE IS-T1

BT IMAGING'S NEW WAFER THICKNESS SYSTEM

WE WERE UNHAPPY WITH COST AND PERFORMANCE OF THIRD PARTY MODULES THAT ARE AVAILABLE FOR WAFER THICKNESS MEASUREMENT DURING WAFER AND CELL PRODUCTION. HENCE WE DEVELOPED OUR ON NEW IS-T1 SYSTEM

MEASUREMENT TECHNIQUE

- LASER TRIANGULATION
- 1-3 LASER SENSOR SPOTS
- LASER SPOT SIZE OPTIMIZED FOR ACCURACY AND PRECISION

REPORTS

- THICKNESS
- TOTAL THICKNESS VARIATION
- [IN DEVELOPMENT] WAFER SURFACE ROUGHNESS

EASY TO USE GRAPHICAL USER INTERFACE

- USER ADJUSTABLE INPUT SETTINGS
- RECIPE OPTIONS
- EXPORT DATA TO SCADA AND WIS

INTEGRATES WITH

- ALL BT IMAGING TOOLS
- ANY THIRD PARTY SYSTEM

